TOSHIBA CMOS Linear Integrated Circuit Silicon Monolithic

# TCK2292xG, TCK2297xG

### 2A, 25mΩ Load Switch IC with Slew Rate Control Driver

The TCK2292xG and TCK2297xG are load switch ICs for power management with slew rate control driver featuring

wide input voltage operation from 1.1 to 5.5 V. Switch ON resistance is only 25 m $\Omega$  typical at 5.0 V, -0.5 A load condition and these feature a slew rate control driver. TCK2292xG has output auto-discharge function. Output current type is available on 2 A.

This device is available in 0.4 mm pitch ultra small package WCSP6E (0.8 mm x 1.2 mm, t: 0.59 mm (max)) .Thus this devices is ideal for portable applications that require high-density board assembly such as cellular phone.

## Feature

- Wide input voltage operation: V<sub>IN</sub> = 1.1 to 5.5 V
- Low ON resistance:

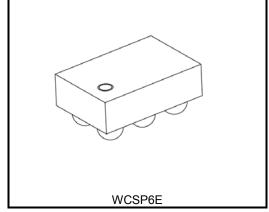
 $R_{ON}$  = 25 m $\Omega$  (typ.) at  $V_{IN}$  = 5.0 V,  $I_{OUT}$  = -0.5 A

 $R_{ON}$  = 31  $m\Omega$  (typ.) at  $V_{IN}$  = 3.3 V,  $I_{OUT}$  = -0.5 A

 $R_{ON}$  = 52 m $\Omega$  (typ.) at  $V_{IN}$  = 1.8 V,  $I_{OUT}$  = -0.5 A

 $R_{ON} = 104 \text{ m}\Omega$  (typ.) at  $V_{IN} = 1.2 \text{ V}$ ,  $I_{OUT} = -0.5 \text{ A}$ 

- Low Quiescent Current: I<sub>Q</sub> = 0.1 μA (typ.) at I<sub>QUT</sub> = 0 mA(TCK22921G, TCK22971G)
- · Slew Rate Control circuit
- Output auto-discharge (Option)
- · Reverse current blocking
- Pull down connection between Control and GND(Option)
- Ultra small package: WCSP6E (0.8mm x 1.2mm, t: 0.59mm(max))



Weight: 1 mg (typ.)



# **Function Table**

	Function						
Part number	Rise time @VIN=5V	Reverse current blocking (SW OFF state)	Output auto-discharge Control pin polarity		Control pin connection	Device Marking	
TCK22921G	4.5 µs	Built in	Built in	Active High	Pull down	1R	
TCK22922G	666 µs	Built in	Built in	Active High	Pull down	2R	
TCK22923G	1364 µs	Built in	Built in	Active High	Pull down	3R	
TCK22925G	3380 µs	Built in	Built in	Active High	Pull down	4R	
TCK22971G	4.5 µs	Built in	N/A	Active High	Pull down	5R	
TCK22972G	666 µs	Built in	N/A	Active High	Pull down	6R	
TCK22973G	1364 µs	Built in	N/A	Active High	Pull down	7R	
TCK22974G	3380 µs	Built in	N/A	Active High	Pull down	8R	
TCK22975G	666 µs	Built in	N/A	Active Low	Open	9R	

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#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating		Unit				
Input voltage	VIN	-0.3 to 6.0		-0.3 to 6.0		-0.3 to 6.0		V
Control voltage	V <sub>CT</sub>		V					
Output voltage	Vout		-0.3 to 6.0					
Output ourrant	lout	DC	2.0	A				
Output current		Pulse	3.0 (Note1)	A				
Power dissipation	PD		800 (Note 2)					
Operating temperature range Topr		-40 to 85		°C				
Junction temeperature	Tj	150		°C				
Storage temperature T <sub>stg</sub>		-55 to 150		°C				

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note1: 100 µs pulse, 2% duty cycle

Note2: Rating at mounting on a board Board material: Glass epoxy (FR4)

Board dimension: 40mm x 40mm (both sides of board), t=1.6mm

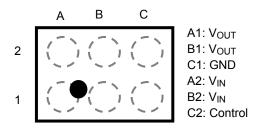
Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

Through hole: diameter 0.5mm x 28

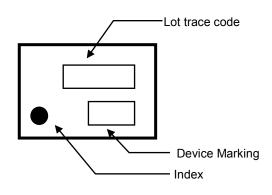
#### **Operating conditions**

Characteristics	Symbol	Condition	Min	Max	Unit	
Input voltage	VIN	_	1.1	5.5	V	
Output voltage	Vout	_		V <sub>IN</sub>	V	
Output current	lout	1.4V < V <sub>IN</sub>		2.0	Α	
Central High level input valtage	VIH	1.2V < V <sub>IN</sub> ≤ 5.5 V	1.0	_	V	
Control High-level input voltage		1.1V ≤ V <sub>IN</sub> ≤1.2 V	0.9	_	V	
Control Low-level input voltage	VIL		_	0.4	V	

#### Pin Assignment(Top view)

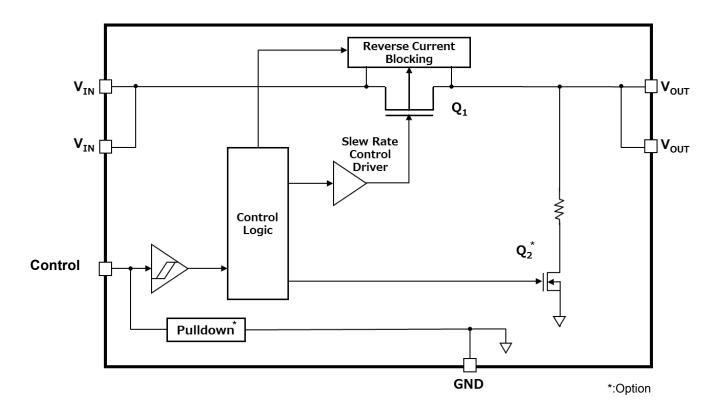


#### Top marking





# **Block Diagram**



# Operation logic table

		TCK22921G	TCK22971G	
		TCK22922G	TCK22972G	TCK22975G
		TCK22923G	TCK22973G	100229730
		TCK22925G	TCK22974G	
Combral	Output Q₁	ON	ON	OFF
Control "High"	Discharge Q <sub>2</sub>	OFF		
Reverse current blocking		Inactive	Inactive	Active
O a ratural	Output Q₁	OFF	OFF	ON
Control "Low"	Discharge Q <sub>2</sub>	ON		_
LOW	Reverse current blocking	Active	Active	Inactive



#### **Electrical Characteristics**

### DC Characteristics (Ta = -40 to 85°C)

91	0 1 1	Test Condition		Ta = 25°C			Ta = -40 to 85°C		
Characteristics	Symbol			Min	Тур.	Max	Min	Max	Unit
	IQ	IOUT = 0 mA (Note 3)	V <sub>IN</sub> = 1.8 V	_	0.1	_	_	_	μΑ
Quiescent current ( ON state)			V <sub>IN</sub> = 3.3 V	_	0.1	_	_	_	μΑ
		(Note 3)	V <sub>IN</sub> = 5.5 V	_	0.1	_	_	0.5	μA
			V <sub>IN</sub> = 1.8 V	_	1.2	_	_	_	μA
Quiescent current ( ON state)	IQ	IOUT = 0 mA	V <sub>IN</sub> = 3.3 V	_	1.3	_	_	_	μΑ
			V <sub>IN</sub> = 5.5 V	_	1.4	_	_	2.5	μA
Quiescent current ( OFF state)	IQ(OFF)	V <sub>IN</sub> = 5.5 V, V <sub>OUT</sub> = OPEN, (Note 4)		_	0.07	_	_	0.4	μΑ
Switch leakage current( OFF state)	ISD(OFF)	V <sub>IN</sub> = 5.5 V, V <sub>OUT</sub> = GND, current through from V <sub>IN</sub> to V <sub>OUT</sub> . (Note 5)		_	0.02	_	_	2	μΑ
Reverse blocking current	I <sub>RB</sub>	V <sub>OUT</sub> = 5.0 V, V <sub>IN</sub> = 0 V		_	0.01	_	_	2	μΑ
			V <sub>IN</sub> = 5.0 V	_	25	_	_	43	
	Ron	I <sub>OUT</sub> = -0.5A	V <sub>IN</sub> = 3.3 V	_	31	_	_	53	
On resistance			V <sub>IN</sub> = 1.8 V	_	52	-	_	83	mΩ
			V <sub>IN</sub> = 1.2 V	_	104	-	_	185	
			V <sub>IN</sub> = 1.1 V	ı	136	ı	_	_	
Output discharge on resistance	RsD	— (Note 6)		_	100	_	_	_	Ω

Note 3: Only applies to the TCK22921G and TCK22971G

Note 4: Except OFF-state switch current

Note 5: Only applies to the TCK22971G, TCK22972G, TCK22973G, TCK22974G and TCK22975G

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Note 6: Only applies to the TCK22921G, TCK22922G, TCK22923G, and TCK22925G



#### **AC Characteristics (Ta = 25°C)**

#### $V_{IN} = 5.0 V$

Characteristics	Symbol	Test Condition(Figure 1)		Min	Тур.	Max	Unit
			TCK22921G	_	4.5	_	
			TCK22971G				
			TCK22922G				
			TCK22972G	-	666	_	
V <sub>OUT</sub> rise time	t <sub>r</sub>	$R_L$ =5 $\Omega$ , $C_L$ =1.0 $\mu$ F	TCK22975G				μs
			TCK22923G		1364	_	
			TCK22973G	_			
			TCK22925G		0000		
			TCK22974G	_	3380	_	
V <sub>OUT</sub> fall time	t <sub>f</sub>	$R_L$ =5Ω , $C_L$ =1.0 $\mu$ F		_	10	1	μs
			TCK22921G		3		
			TCK22971G	_	3	_	
			TCK22922G				
			TCK22972G	_	380	_	
Turn on delay	toN	$R_L$ =5 $\Omega$ , $C_L$ =1.0 $\mu$ F	TCK22975G				μs
			TCK22923G		750	_	
			TCK22973G	_	750		
			TCK22925G		2000		
			TCK22974G	_		_	
Turn off delay	toff	$R_L$ =5 $\Omega$ , $C_L$ =1.0 $\mu$ F		_	10	_	μs

### **AC Waveform**

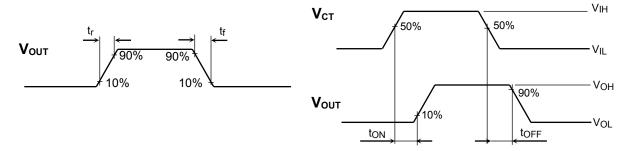


Figure 1 tr, tf, tON, tOFF Waveforms(Active High)

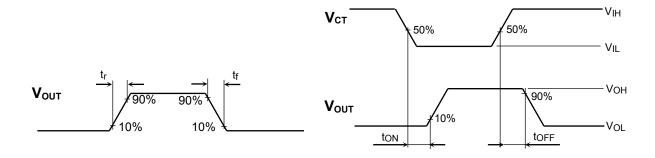


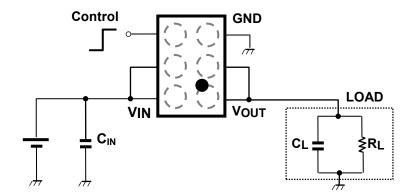
Figure 2 tr, tf, tON, tOFF Waveforms(Active Low)



#### **Application Note**

#### 1. Application circuit example (top view)

The figure below shows the recommended configuration



Control Voltage	Output Voltage
HIGH	ON
LOW	OFF
OPEN	OFF

#### 1) Input and Output capacitor

An input capacitor (CIN) and an output capacitor (COUT) are highly recommended for the stable operation. And it is effective to reduce voltage overshoot or undershoot due to sharp changes in output current and also for improved stability of the power supply. When used, place CIN and COUT more than  $1.0\mu F$  as close to  $V_{IN}$  pin to improve stability of the power supply.

#### 2) Control pin

The Control pin controls both the pass-through p-ch MOSFET and the discharge n-ch MOSFET (only for TCK2292xG), operated by the control voltage and Schmitt trigger. Also, pull down resistance equivalent to a few  $M\Omega$  is connected between Control and GND, thus the load switch IC is in OFF state even when Control pin is OPEN. (except TCK22975G). Products that Control pin is an open connection, please use be sure to fix the potential of the Control pin to High or Low.

#### 2. Reverse current blocking

This device has a built-in Reverse current blocking (SW OFF state) circuit to block reverse current from VOUT to VIN when output n-ch MOSEFT turned off and input voltage is 0V.

#### 3. Instructions and directions for use

This device has a built-in several functions, but these does not assure for the suppression of uprising device operation. In use of these products, please read through and understand dissipation idea for absolute maximum ratings from the above mention or our 'Semiconductor Reliability Handbook'. Then use these products under absolute maximum ratings in any condition. Furthermore, Toshiba recommend inserting failsafe system into the design.



#### 4. Power Dissipation

Power dissipation is measured on the board condition shown below.

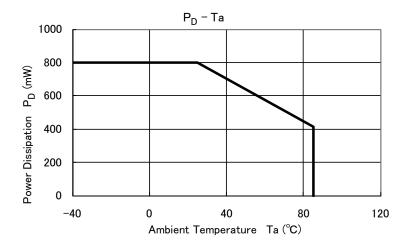
[The Board Condition]

Board material: Glass epoxy (FR4)

Board dimension: 40mm x 40mm (both sides of board), t=1.6mm

Metal pattern ratio: a surface approximately 50%, the reverse side approximately 50%

Through hole: diameter 0.5mm x 28

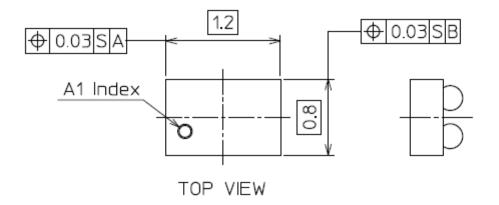


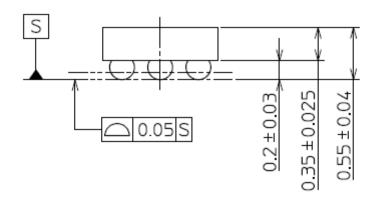
Please allow sufficient margin when designing a board pattern to fit the expected power dissipation. Also take into consideration the ambient temperature, input voltage, output current etc. and applying the appropriate derating for allowable power dissipation during operation.

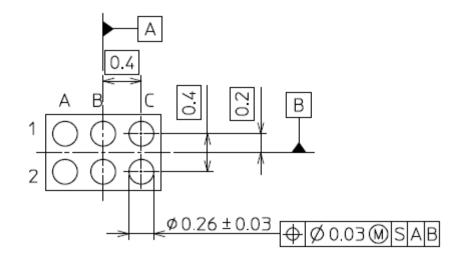
# **TOSHIBA**

# Package dimension

Unit: mm







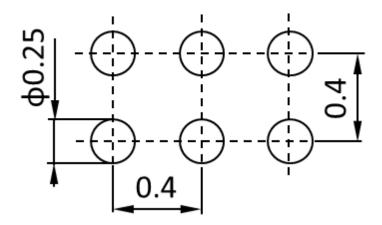
BOTTOM VIEW

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Weight: 1 mg (typ.)

Land pattern dimensions (for reference only)

Unit: mm





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